

04-04-2001



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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

## 1. Name of conveying party(ies):

UNIVERSITY OF MICHIGAN

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

## 3. Nature of conveyance:

- ☐ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☒ Other Confirmatory License

Execution Date(s): 5 MARCH 2001

- ☒ This instrument should be recorded on the governmental register in accordance with 37 CFR 7.1(e)(1).

## 2. Name and address of receiving party(ies):

Name: UNITED STATES AIR FORCEInternal Address: AFRL/IFOJStreet Address: 26 ELECTRONIC PARKWAYCity: ROMEState: NEW YORK Zip: 13441-4514Additional name(s) & address(es) attached? ☐ Yes ☒ No

## 4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: \_\_\_\_\_

## A. Patent Application No.(s):

09/204,473

## B. Patent No.(s):

Additional numbers attached? ☐ Yes ☒ No

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: HAROLD L. BURSTYNInternal Address: AFRL/IFOJStreet Address: 26 ELECTRONIC PARKWAYCity: ROMEState: NEW YORK ZIP: 13441-4514

## 6. Total number of applications and patents involved:

17. Total fee (37 CFR 3.41) .....\$ 0☐ Enclosed ☒ Not applicable

The instrument to be recorded is not an instrument affecting title (37 CFR 7.1(e)(2) and (j)).

## 8. Deposit account number:

(Attach duplicate copy of this page if paying by deposit account)

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## 9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

JUDITH M. DECKER

Name of person signing

Signature

Date

Total number of pages including cover sheet, attachments, and document:

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LICENSE TO THE UNITED STATES GOVERNMENT

This instrument confers to the United States Government, as represented by the Department of Defense, a nonexclusive, nontransferable, irrevocable, paid-up license to practice or have practiced on its behalf throughout the world the following subject invention. This license will extend to all divisions or continuations of the patent application and all patents or reissues which may be granted thereon:

Title: Localized Silicon Fusion and Eutectic Bonding for MEMS  
Fabrication and Packaging

Inventor(s): Liwei Lin, Yu-Fong Chen and Khalil Najafi

Patent Application

Serial No.: 09/204,473

Filing Date: March 5, 2001

Issue Date:

Patent No.:

Title: Process for Making Microstructures and Microstructures  
Made Thereby

Country, if other  
than United States: None

This subject invention was conceived or first actually reduced to practice in performance of a government-funded project, Defense Advanced Research Projects Agency Grant No. **F30602-98-2-0227**

Principal rights to this subject invention have been left with the Licensor: The Regents of the University of Michigan, subject to the provisions of 37 CFR 401 and 45 CFR 8.

Signed: Marvin G. Parnes Date: 3-5-01

Name: Marvin G. Parnes

Title: Associate Vice President for Research